

Listing of Claims

1. (Previously amended) A computing device, comprising:
a first member having a first structural element and a first conductive element;
a second member having a second structural element and a second conductive element;
and
a means for electrically and structurally coupling the elements of the first and second members together so as to form a singular composite structure that both supports the computing device and shields the computing device from electronic emissions.
2. (Cancelled)
3. (Previously amended) The computing device as recited in claim 1 wherein the singular composite structure is used to enclose internal components of the computing device.
4. (Original) The computing device as recited in claim 1 wherein the means has a liquid state for flowing between the first and second members, and a solid state for permanently attaching itself to the first and second members.
5. (Original) The computing device as recited in claim 4 wherein the means includes a structural glue and a conductive paste.
6. (Previously amended) The computing device as recited in claim 5 wherein the structural glue is arranged to structurally attach the structural elements of the first and second members, and wherein the conductive paste is arranged to electrically connect the conductive elements of the first and second members.
7. (Original) The computing device as recited in claim 6 wherein the structural glue is arranged to fill a gap between the structural elements of the first and second members, and wherein the conductive paste is arranged to seal an interface between the conductive elements of the first and second members.
8. (Original) The computing device as recited in claim 1 wherein the first member is formed from a conductive material, wherein the second member is formed from a non-conductive

material, and wherein the conductive element of the second member is a conductive layer that is formed on the structural element of the second member.

9. (Currently amended) A component of a computer enclosure, comprising:

a casing;

a frame for supporting the casing, the casing and the frame being configured to at least partially enclose parts of a computing device;

a glue disposed between the casing and the frame, the glue structurally attaching the casing and the frame to form a singular composite structure, the glue being arranged to absorb geometric variations found in the frame or casing so as to meet a predetermined geometry of the component, the casing and the frame being arranged to provide an adjustable gap therebetween for the placement of the glue, the dimensions of the glue conforming to the adjustable gap to reduce tolerance variability in the glued component.

10. (Cancelled)

11. (Cancelled)

12. (Previously amended) The component as recited in claim 9 wherein the glue has a compliant state arranged for filling the gap, and wherein the glue has a rigid state for structurally binding the first and second members together.

13. (Original) The component as recited in claim 12 wherein the glue is a two part epoxy.

14. (Previously amended) The component as recited in claim 9 wherein the glue substantially eliminates the use of mechanical fasteners, which are used to attach the first and second members.

15. (Previously amended) The component as recited in claim 9 wherein the casing is formed from a first material, and wherein the frame is formed from a second material that is different than the first material.

16. (Previously amended) The component as recited in claim 9 wherein the casing is formed from a plastic material, and wherein the frame is formed from a metallic material.

17. (Cancelled)
18. (Previously amended) The component as recited in claim 9 wherein a first surface of the casing is configured to be flush with a second surface of the frame.
19. (Previously amended) The component as recited in claim 9 wherein a first surface of the casing is configured to be offset from a second surface of the frame.
20. (Previously amended) A component of a computer enclosure comprising:
a first member having a first conductive surface;
a second member having a second conductive surface; and
a conductive bridge electrically bonding the first and second conductive surfaces and electrically sealing an interface between the first and second conductive surfaces so as to form a singular conductive structure for shielding electronic emissions.
21. (Original) The component as recited in claim 20 wherein the conductive bridge is a conductive paste.
22. (Original) The component as recited in claim 21 wherein the conductive paste has a compliant state arranged for sealing the interface, and a rigid state for electrically bonding the conductive surfaces of the first and second members together.
23. (Original) The component as recited in claim 22 wherein the conductive paste is a metal filled electrically conductive ink.
24. (Original) The component as recited in claim 20 wherein the first member is formed from a first material, and wherein the second member is formed from a second material that is different than the first material.
25. (Original) The component as recited in claim 24 wherein the first member is formed from a conductive material, wherein the second member is formed from a non-conductive material that is selectively coated with a conductive layer, and wherein the conductive bridge electrically

connects and electrically seals an interface between the conductive material of the first member and the conductive layer of the second member.

26. (Original) The component as recited in claim 25 wherein the first member is formed from a first metallic material, wherein the second member is formed from a plastic material, and wherein the conductive layer is formed from a second metallic material.

27. (Original) The component as recited in claim 26 wherein the plastic material is a carbon fiber plastic, the second metallic material is a nickel plated layer, and the metallic material is titanium sheet metal.

28. (Original) The component as recited in claim 27 wherein the conductive bridge is formed from a nickel filled electrically conductive ink.

29. (Original) The component as recited in claim 28 wherein the nickel filled electrically conductive ink has viscosity between about 5000 centipoise to about 10000 centipoise.

30. (Original) The component as recited in claim 20 wherein the first member is a casing, wherein the second member is a frame for supporting the casing, and wherein the casing and the frame are configured to at least partially enclose parts of a computing device.

31. (Currently amended) A portable computer enclosure, comprising:

a first case configured to at least partially enclose internal components of the portable computer, the first case including a first member ~~formed from a first material~~ and a second member ~~formed from a second material that is different than the first material~~, the first member being structurally glued to the second member to form a first composite structure, the glue having properties that allow it to compensate for tolerances in the first and second members so as to produce a desired first case dimension, the first case being configured to at least partially shield electronic emissions produced by the internal components, the first member being formed from a first conductive material, the second member being formed from a non-conductive material that is coated with a second conductive material that is different than the first conductive material, the interface between the first member and second member being electrically sealed via a conductive paste so as to shield the interface from electronic emissions; and

a second case configured to mechanically cooperate with the first case to fully enclose internal components of the portable computer, the second case including a third member and a fourth member, the third member being glued to the fourth member to form a second composite structure, the glue having properties that allow it to compensate for tolerances in the third and fourth members so as to produce a desired second case dimension, the second case being configured to at least partially shield electronic emissions produced by the internal components, the third member being formed from a third conductive material, the fourth member being formed from a second non-conductive material that is coated with a fourth conductive material that is different than the third conductive material, the interface between the third member and fourth member being electrically sealed via a second conductive paste so as to shield the interface from electronic emissions,

wherein when the first and second cases mechanically cooperate with one another to form an enclosure having a predetermined geometry that is based at least in part on the desired first case dimension and the desired second case dimension and electrically cooperate with one another to fully shield the electronic emissions produced by the internal components.

32-56. (Cancelled)

57. (Currently amended) A computing device, comprising:

a first structural member having a first conductive portion;

a second structural member having a second conductive portion; and

a joint configured to electrically bond the first and second conductive portions together in order to form a single conductive structure for shielding electronic emissions around the computing device and to structurally attach the first and second structural members together in order to form a single composite structure for housing at least a portion of the computing device.

58. (Previously added) The computing device as recited in claim 57 wherein the joint is rigid.

59-62. (Cancelled)

63. (New) The computing device as recited in claim 58 wherein the joint includes a structural glue for structurally attaching the first and second structural members and a conductive paste for electrically bonding the first and second conductive portions.

64. (New) The computing device as recited in claim 63 wherein the joint is formed by dispensing the glue on the first or second structural member, applying a force to sandwich the glue between the first and second structural members, and allowing the glue to cure when the first and second structural members are placed in a predetermined position relative to one another.

65. (New) The computing device as recited in claim 64 wherein the glue is a two part epoxy.

66. (New) The computing device as recited in claim 64 wherein the first and second structural members are arranged to form an adjustable gap for placement of the glue, the uncured glue being arranged to absorb geometric variations found in the first and second structural members so as to meet a predetermined geometry of the single composite structure.

67. (New) The computing device as recited in claim 63 wherein the joint is formed by dispensing the conductive paste on the first or second conductive portion, flowing the conductive paste between the first and second conductive portions, and allowing the conductive paste to cure so as to electrically seal an interface between the first and the second conductive portions.

68. (New) The computing device as recited in claim 67 wherein the conductive paste is dispensed along a predetermined path that corresponds to the area of desired electrical contact between the first and second conductive portions.

69. (New) The computing device as recited in claim 67 wherein the conductive paste is a metal filled electrically conductive ink.

70. (New) The computing device as recited in claim 63 wherein the first structural member is formed from a conductive material and wherein the second structural member is formed from a non conductive material, the first conductive portion being part of the first structural member, the second conductive portion being selectively coated on the second structural member.

71. (New) The computing device as recited in claim 69 wherein the first structural member is formed from titanium, the second structural member is formed from carbon fiber, and the second conductive portion is Nickel based.

72. (New) The computing device as recited in claim 57 wherein the single composite structure houses a microprocessor.